United States Patent [19]

Asanuma

[11] **Des. 266,074**

[45] ** **Sep. 7, 1982**

[54] **HEAT RELEASING PLATE FOR MOUNTING SEMICONDUCTOR COMPONENTS**

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[73] Assignee: **Showa Aluminum Kabushiki Kaisha,** Osaka, Japan

[**] Term: **14 Years**

[21] Appl. No.: **154,975**

[22] Filed: **May 30, 1980**

[30] **Foreign Application Priority Data**

Mar. 31, 1981 [TW] Taiwan 6930603

[51] **Int. Cl.** .... **D13—03**

[52] **U.S. Cl.** **D13/23**

[58] **Field of Search** .... D13/23; 165/80 R, 80 A, 165/80 B, 80 D; 357/81; 174/16 HS

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for heat releasing plate for mounting semiconductor components, as shown and described.

DESCRIPTION

FIG. **1** is a front view of the heat releasing plate for mounting semi-conductor components showing the new design;

FIG. **2** is a plan view thereof;

FIG. **3** is a rear view thereof;

FIG. **4** is a bottom view thereof;

FIG. **5** is a right side view thereof; and

FIG. **6** is a sectional view taken on line **6—6** of FIG. **1.**

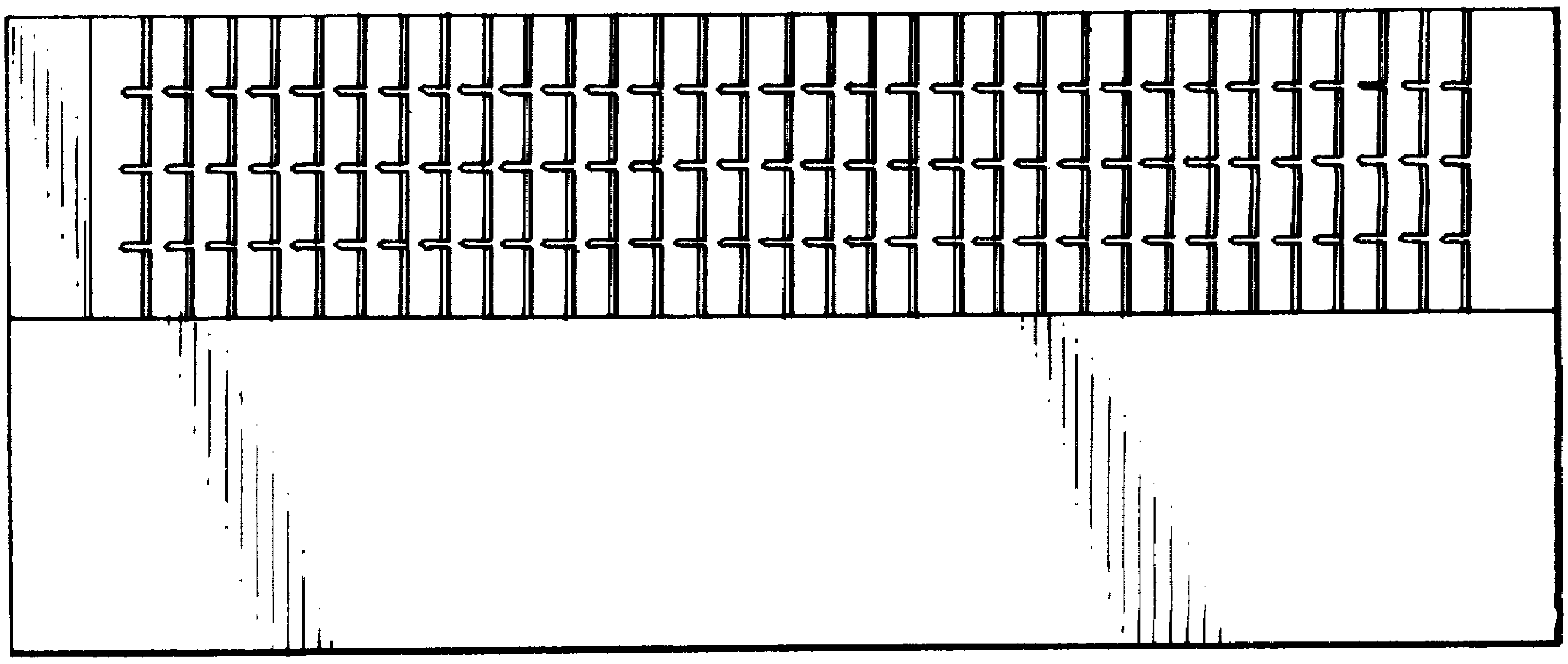

FIG. 1.

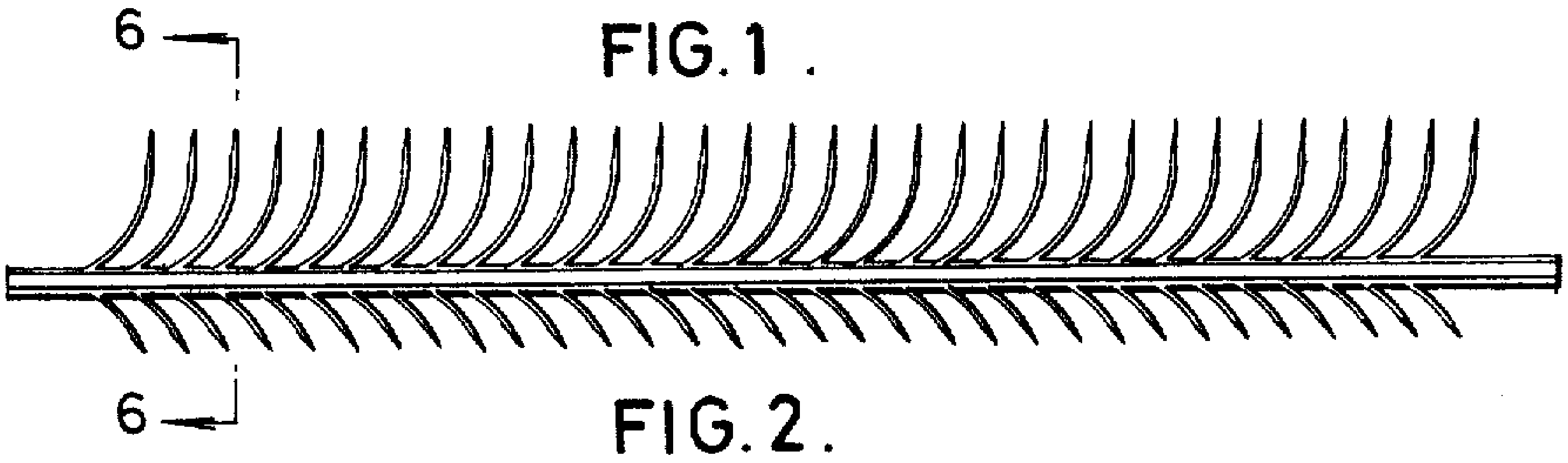

FIG. 2.

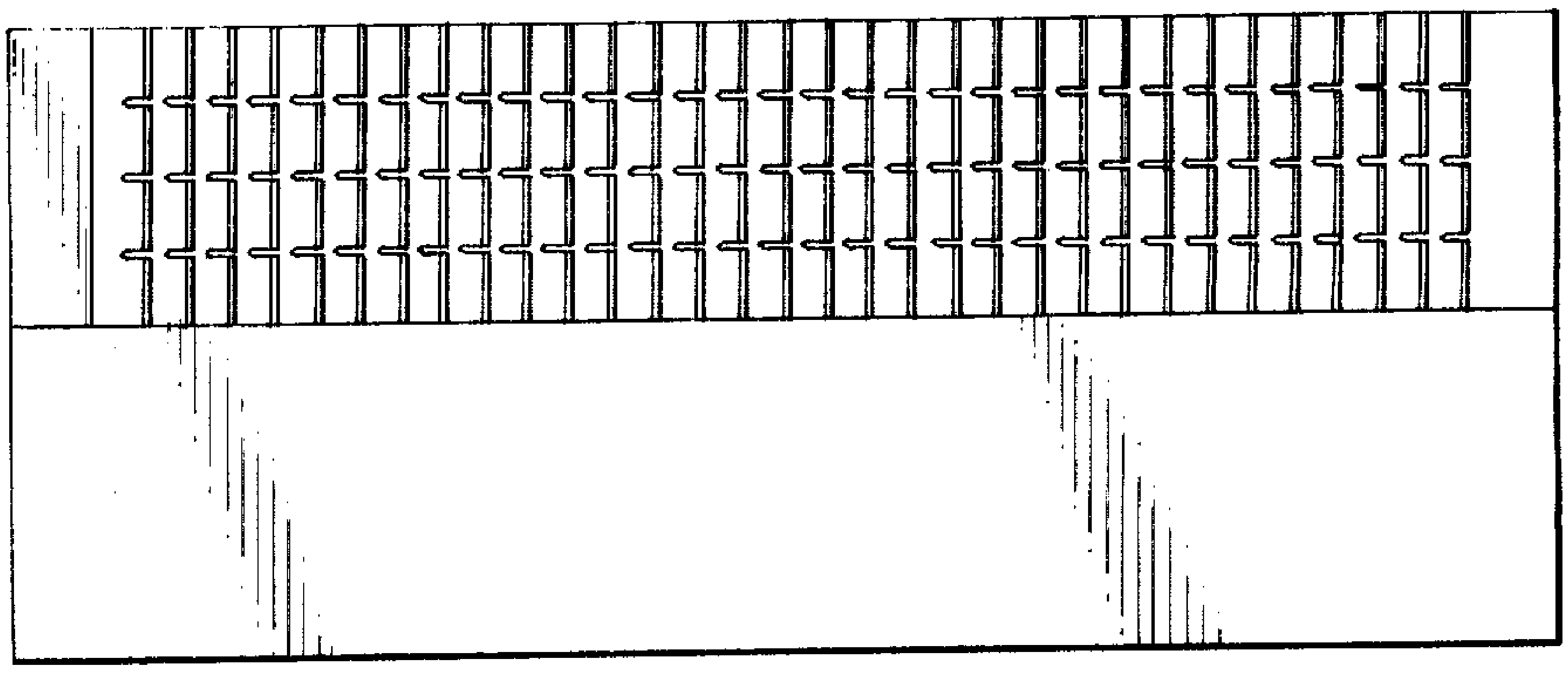

FIG. 3.

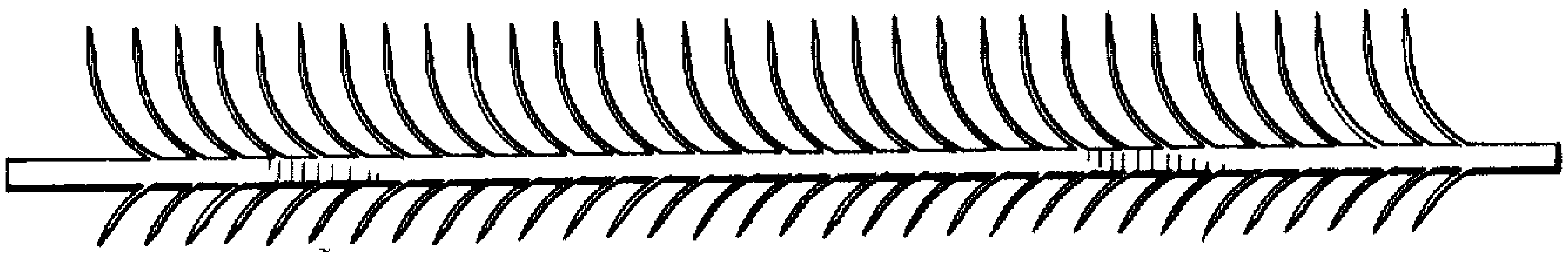

FIG. 4.

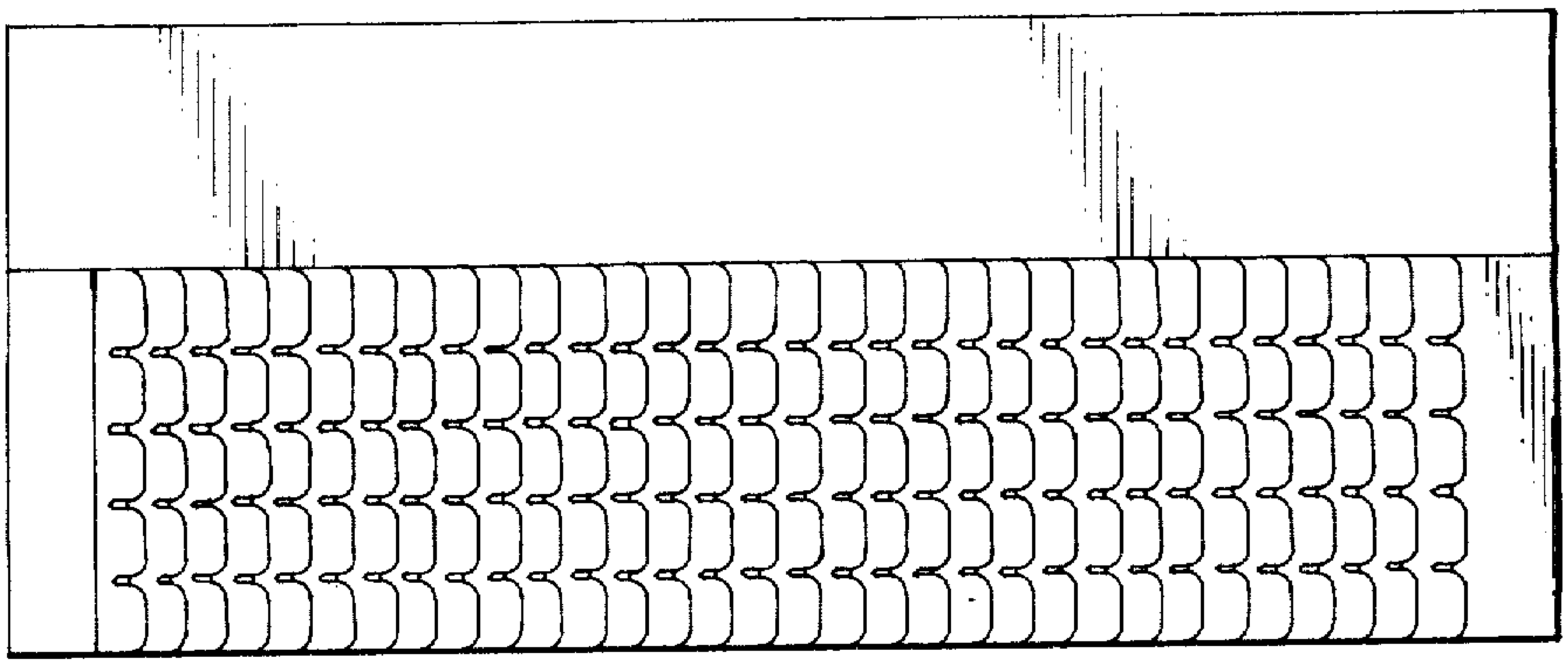

FIG. 5.

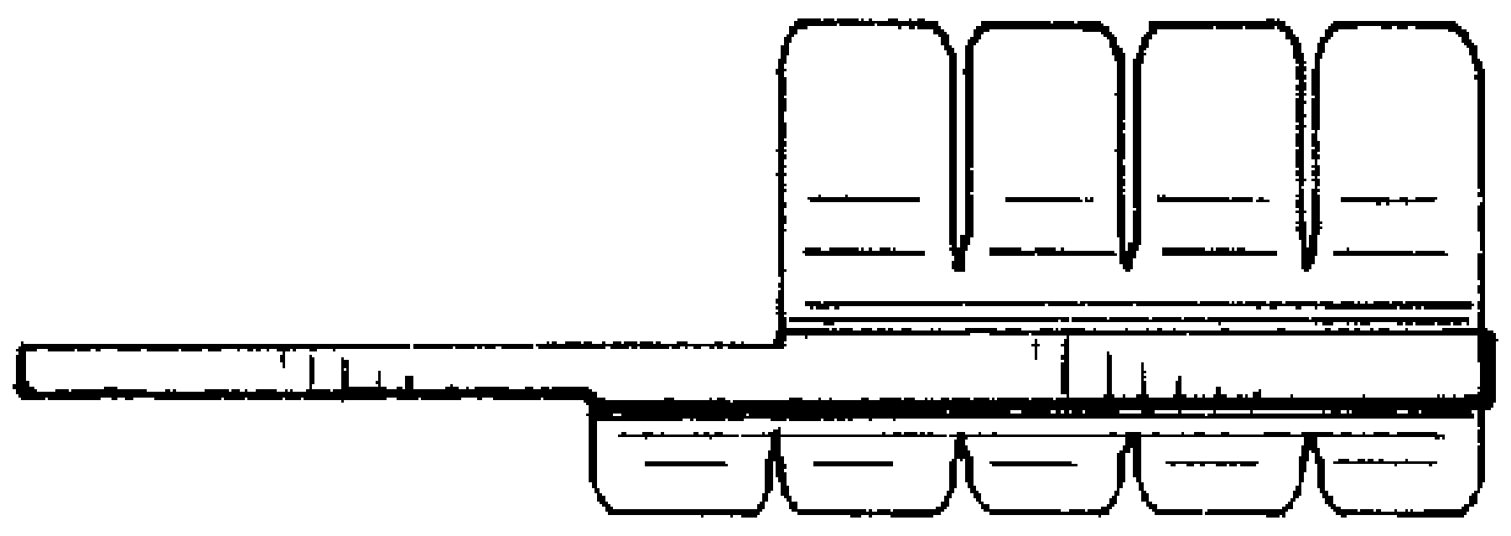

FIG. 6.